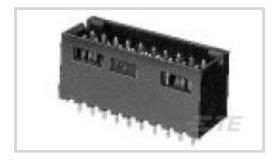
# 103168-7 - ACTIVE

### AMPMODU | AMPMODU Headers

TE Internal #: 103168-7 PCB Mount Header, Vertical, Board-to-Board, 18 Position, 2.54 mm [.1 in] Centerline, Fully Shrouded, Gold, Through Hole - Solder, AMPMODU Headers

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# PCB Connector Assembly Type: PCB Mount Header

PCB Mount Orientation: Vertical

Connector System: Board-to-Board

Number of Positions: **18** 

Number of Rows: 2

## Features

### **Product Type Features**

PCB Connector Assembly Type

Connector System

Header Type

PCB Mount Header

Board-to-Board

Fully Shrouded



Connector & Contact	Terminates To
---------------------	---------------

Printed Circuit Board

### **Configuration Features**

Connector Contact Load Condition	Fully Loaded
PCB Mount Orientation	Vertical
Number of Positions	18
Number of Rows	2
Board-to-Board Configuration	Parallel
Electrical Characteristics	
Insulation Resistance	5000 ΜΩ
Dielectric Withstanding Voltage (Max)	750 Vrms
Body Features	
Connector Profile	Standard
Primary Product Color	Black
Contact Features	
Mating Square Post Dimension	.64 mm[.025 in]

PCB Mount Header, Vertical, Board-to-Board, 18 Position, 2.54 mm [.1 in] Centerline, Fully Shrouded, Gold, Through Hole - Solder, AMPMODU Headers



PCB Contact Termination Area Plating Material Thickness	2.54 – 5.08 μm[100 – 200 μin]
Contact Shape & Form	Square
Contact Underplating Material	Nickel
PCB Contact Termination Area Plating Material	Tin-Lead
Contact Base Material	Phosphor Bronze
Contact Mating Area Plating Material	Gold
Contact Mating Area Plating Material Thickness	.762 μm[30 μin]
Contact Type	Pin
Contact Current Rating (Max)	3 A
Termination Features	
Square Termination Post & Tail Dimension	.64 mm[.025 in]
Termination Post & Tail Length	3.18 mm[.125 in]
Termination Method to Printed Circuit Board	Through Hole - Solder
Mechanical Attachment	
Mating Retention	With
Mating Retention Type	Detent Window
Mating Alignment	With

Mating Alignment Type

Polarizatio

Mating Alignment Type	Polarization
PCB Mount Retention	Without
PCB Mount Alignment	Without
Connector Mounting Type	Board Mount
Housing Features	
Centerline (Pitch)	2.54 mm[.1 in]
Housing Material	Thermoplastic
Dimensions	
Row-to-Row Spacing	2.54 mm[.1 in]
PCB Thickness (Recommended)	1.4 mm[.055 in]
Usage Conditions	
Housing Temperature Rating	Standard
Operating Temperature Range	-65 – 105 °C[-85 – 221 °F]
Operation/Application	
Circuit Application	Signal

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PCB Mount Header, Vertical, Board-to-Board, 18 Position, 2.54 mm [.1 in] Centerline, Fully Shrouded, Gold, Through Hole - Solder, AMPMODU Headers



### **Industry Standards**

Agency/Standard	CSA			
Approved Standards	CSA LR7189, UL E28476			
UL Flammability Rating	UL 94V-0			
Packaging Features				
Packaging Quantity	96			
Packaging Type	Tray			
Product Compliance For compliance documentation, visit the product page on TE.com> EU RoHS Directive 2011/65/EU	Not Compliant			
EU ELV Directive 2000/53/EC	Not Compliant			
China RoHS 2 Directive MIIT Order No 32, 2016	Restricted Materials Above Threshold			
EU REACH Regulation (EC) No. 1907/2006	Current ECHA Candidate List: JUNE 2023 (235) Candidate List Declared Against: JAN 2022 (223) SVHC > Threshold: Pb (40% in Component Part) Article Safe Usage Statements: Do not eat, drink or smoke when using this product. Wash thoroughly after			

handling. Recycle if possible and dispose of the article by following all applicable governmental regulations relevant to your geographic location.

### Halogen Content

Low Halogen - Br, Cl, F, I < 900 ppm per homogenous material. Also BFR/CFR/PVC Free

Wave solder capable to 240°C

Solder Process Capability

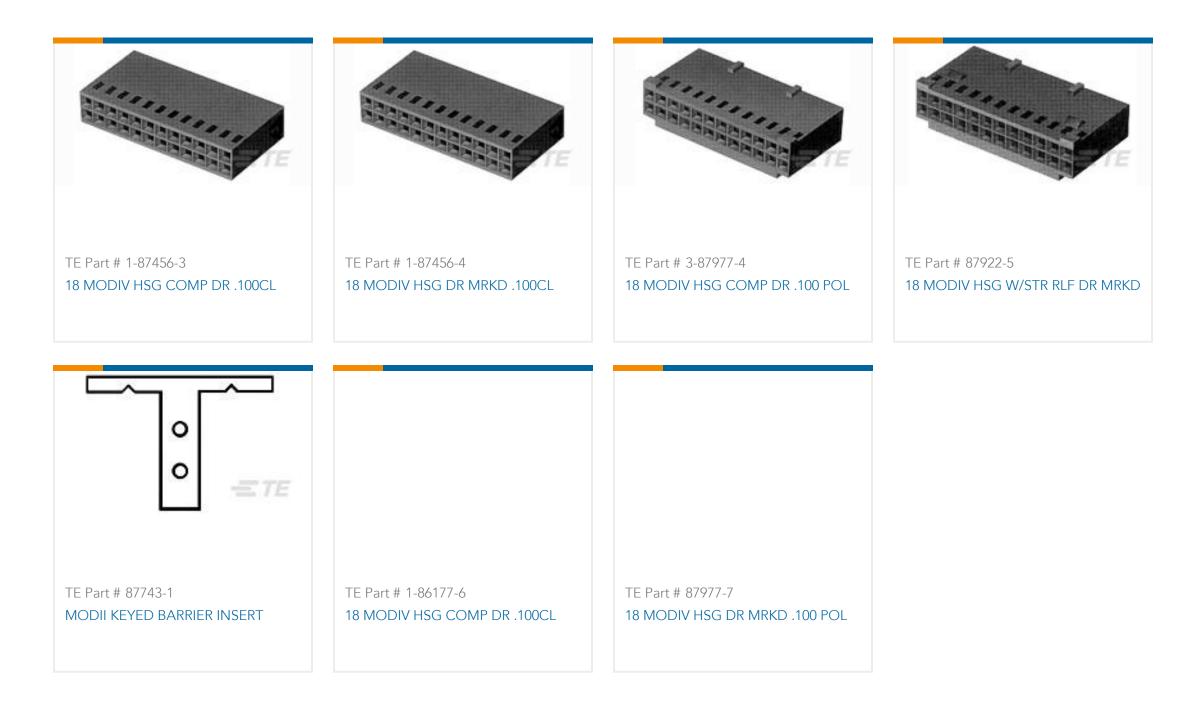
Product Compliance Disclaimer

This information is provided based on reasonable inquiry of our suppliers and represents our current actual knowledge based on the information they provided. This information is subject to change. The part numbers that TE has identified as EU RoHS compliant have a maximum concentration of 0.1% by weight in homogenous materials for lead, hexavalent chromium, mercury, PBB, PBDE, DBP, BBP, DEHP, DIBP, and 0.01% for cadmium, or qualify for an exemption to these limits as defined in the Annexes of Directive 2011/65/EU (RoHS2). Finished electrical and electronic equipment products will be CE marked as required by Directive 2011/65/EU. Components may not be CE marked. Additionally, the part numbers that TE has identified as EU ELV compliant have a maximum concentration of 0.1% by weight in homogenous materials for lead, hexavalent chromium, and mercury, and 0.01% for cadmium, or qualify for an exemption to these limits as defined in the Annexes of Directive 2000/53/EC (ELV). Regarding the REACH Regulation, the information TE provides on SVHC in articles for this part number is based on the latest European Chemicals Agency (ECHA) 'Guidance on requirements for substances in articles' posted at this URL: https://echa.europa.eu/guidance-documents/guidance-on-reach

# **Compatible Parts**

PCB Mount Header, Vertical, Board-to-Board, 18 Position, 2.54 mm [.1 in] Centerline, Fully Shrouded, Gold, Through Hole - Solder, AMPMODU Headers

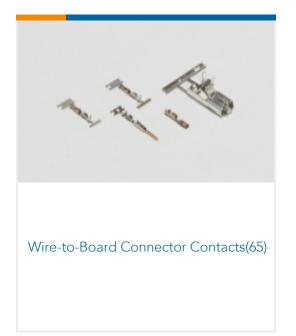




# Also in the Series AMPMODU Headers



Connector Caps & Covers(1)	Connector Hardware(2)	PCB Headers & Receptacles(4843)	& Housings(5)	

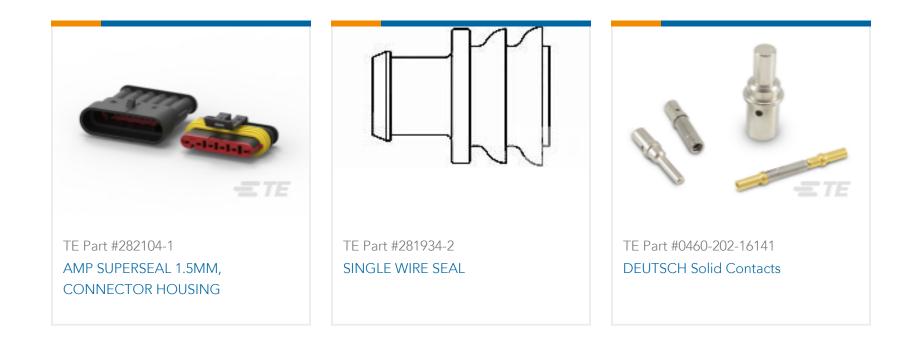


# Customers Also Bought



PCB Mount Header, Vertical, Board-to-Board, 18 Position, 2.54 mm [.1 in] Centerline, Fully Shrouded, Gold, Through Hole - Solder, AMPMODU Headers





# Documents

## Product Drawings 18 MODII HDR DRST SHRD .100CL

English

### **CAD** Files

3D PDF

3D

**Customer View Model** 

ENG\_CVM\_CVM\_103168-7\_M.2d\_dxf.zip

English

Customer View Model

ENG\_CVM\_CVM\_103168-7\_M.3d\_igs.zip

English

Customer View Model

### ENG\_CVM\_CVM\_103168-7\_M.3d\_stp.zip

English

By downloading the CAD file I accept and agree to the **Terms and Conditions** of use.

Product Specifications Product Specification

English